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a plurality of electrical connect points electrically connecting said chip packages with said substrate;

a plurality of electrical connect pins; and

a package material enclosing said substrate, said connect points and said chip packages.

But this
49. (Amended) A multi-chip module package structure comprising:

a substrate;

at least a bare chip;

at least one chip package, said chip package being a packaged chip module having a bare chip packaged and embedded therein, burn-in tested and function tested;

a plurality of electrical connect points electrically connecting said bare chip and said at least one chip package with said substrate;

a plurality of electrical connect pins; and

a package material enclosing said substrate, said connect points, said bare chip and said at least one chip package.